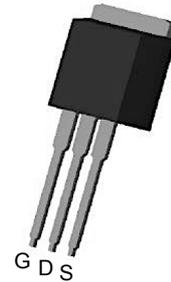
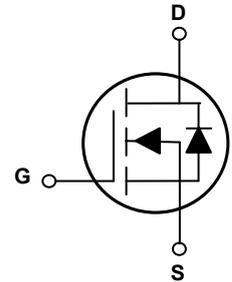


## Main Product Characteristics

$V_{(BR)DSS}$	40V
$R_{DS(ON)}$	22m $\Omega$ (Max.)
$I_D$	30A



TO-262-3L



Schematic Diagram

## Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



## Description

The GSFDT4022 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

## Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	40	V
Gate-to-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current, @ Steady-State ( $T_C=25^\circ\text{C}$ ) <sup>1</sup>	$I_D$	30	A
Continuous Drain Current, @ Steady-State ( $T_C=100^\circ\text{C}$ )		21	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	120	A
Power Dissipation ( $T_C=25^\circ\text{C}$ )	$P_D$	50	W
Linear Derating Factor ( $T_C=25^\circ\text{C}$ )		0.40	W/ $^\circ\text{C}$
Single Pulse Avalanche Energy <sup>3</sup>	$E_{AS}$	49	mJ
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	2.5	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Ambient (PCB Mounted, Steady-State) <sup>4</sup>	$R_{\theta JA}$	62.0	$^\circ\text{C/W}$
Operating Junction and Storage Temperature Range	$T_J/T_{STG}$	-55 to +150	$^\circ\text{C}$

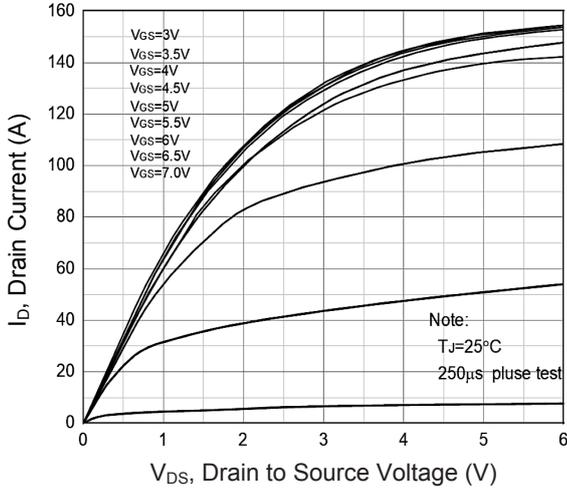
**Electrical Characteristics** ( $T_C=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>On / Off Characteristics</b>						
Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	40	-	-	V
Drain-to-Source Leakage Current	$I_{DSS}$	$V_{DS}=40V, V_{GS}=0V$	-	-	1	$\mu A$
		$T_J=125^\circ C$	-	-	20	
Gate-to-Source Forward Leakage	$I_{GSS}$	$V_{GS}=20V$	-	-	100	nA
		$V_{GS}=-20V$	-	-	-100	
Static Drain-to-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=20A$	-	16	22	m $\Omega$
		$V_{GS}=4.5V, I_D=15A$	-	20	28	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.1	1.6	2.9	V
<b>Dynamic and Switching Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{GS}=0V, V_{DS}=30V, f=1MHz$	-	2200	-	pF
Output Capacitance	$C_{oss}$		-	140	-	
Reverse Transfer Capacitance	$C_{rss}$		-	70	-	
Total Gate Charge	$Q_g$	$I_D=20A, V_{DS}=30V, V_{GS}=10V$	-	48	-	nC
Gate-to-Source Charge	$Q_{gs}$		-	9.2	-	
Gate-to-Drain ("Miller") Charge	$Q_{gd}$		-	10	-	
Turn-On Delay Time	$t_{d(on)}$	$V_{GS}=10V, V_{DS}=30V, I_D=20A, R_{GEN}=3\Omega$	-	11	-	nS
Rise Time	$t_r$		-	26	-	
Turn-Off Delay Time	$t_{d(off)}$		-	87	-	
Fall Time	$t_f$		-	75	-	
Gate Resistance	$R_g$	$f=1MHz$	-	2.2	-	$\Omega$
<b>Drain-Source Ratings and Characteristics</b>						
Continuous Source Current (Body Diode)	$I_S$	MOSFET symbol showing the integral reverse p-n junction diode.	-	-	30	A
Pulsed Source Current (Body Diode)	$I_{SM}$		-	-	120	A
Diode Forward Voltage	$V_{SD}$	$I_S=20A, V_{GS}=0V$	-	1.0	1.2	V
Reverse Recovery Time	$t_{rr}$	$T_J=25^\circ C, I_F=20A, di/dt=100A/\mu s$	-	14	-	nS
Reverse Recovery Charge	$Q_{rr}$		-	16.5	-	nC

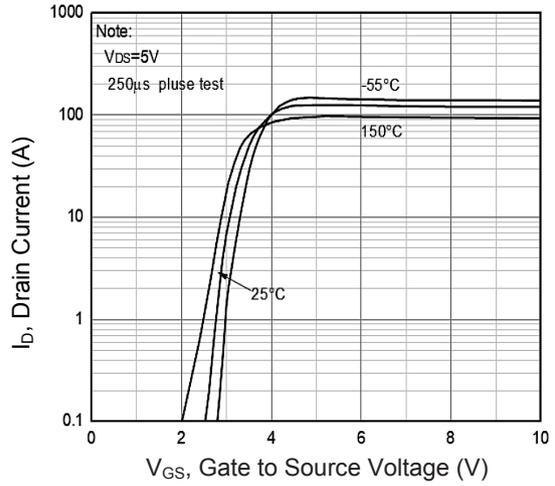
Notes:

1. Pulse test: Pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
2. Repetitive rating; pulse width limited by max. junction temperature.
3.  $L=0.5mH, V_{DD}=30V, R_G=25\Omega, T_J=25^\circ C$ .
4. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch.

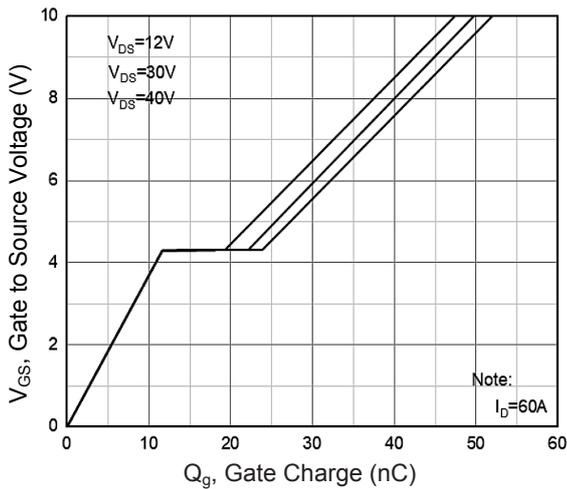
**Typical Electrical and Thermal Characteristic Curves**



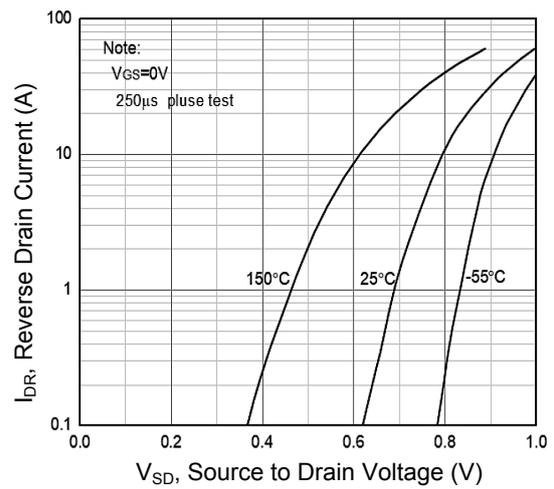
**Figure 1. Output Characteristics**



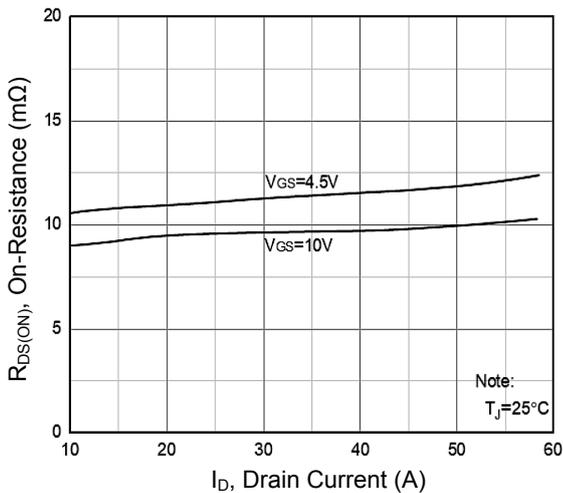
**Figure 2. Transfer Characteristics**



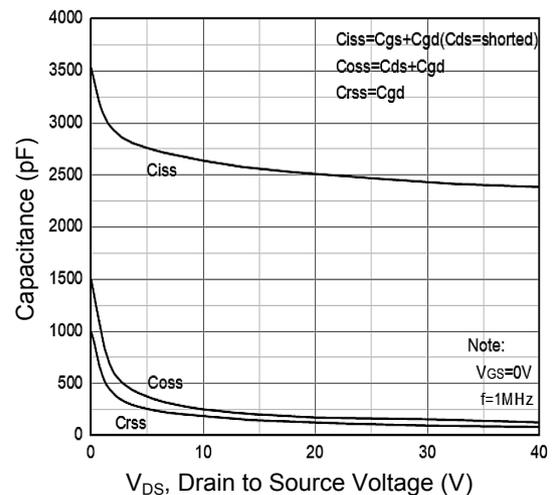
**Figure 3. Gate Charge Characteristics**



**Figure 4. Body Diode Characteristics**

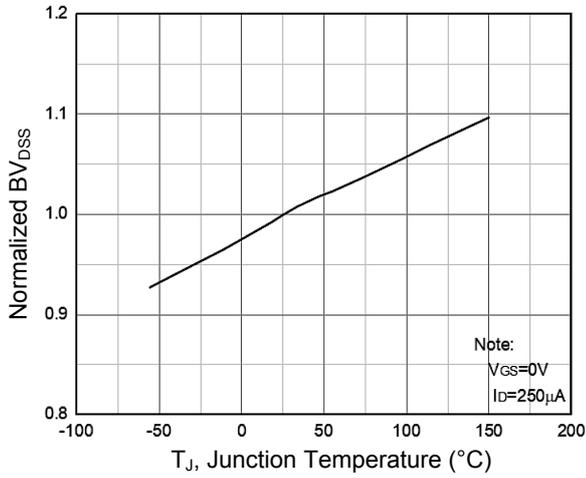


**Figure 5. On-Resistance vs. Drain Current**

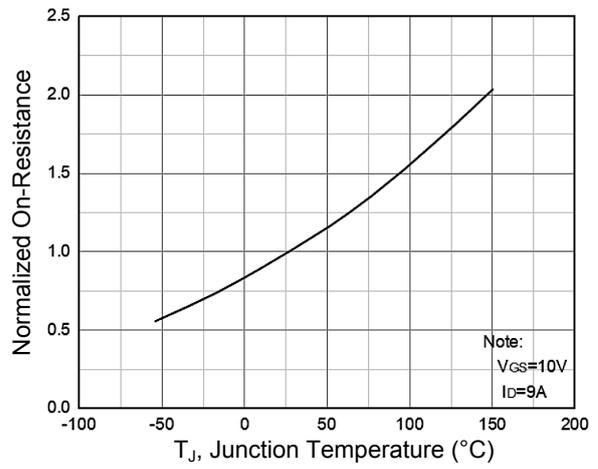


**Figure 6. Capacitance Characteristics**

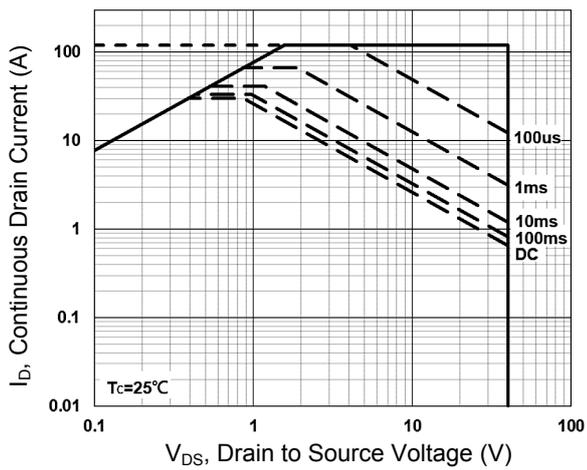
**Typical Electrical and Thermal Characteristic Curves**



**Figure 7. Normalized  $BV_{DSS}$  vs.  $T_J$**

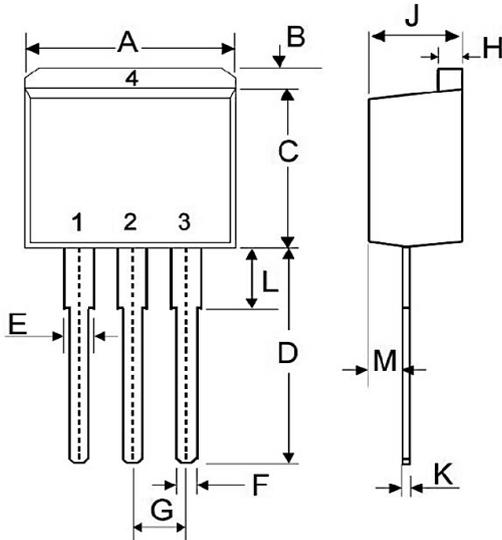


**Figure 8. Normalized  $R_{DS(ON)}$  vs.  $T_J$**



**Figure 9. Maximum Safe Operation Area**

**Package Outline Dimensions (TO-262-3L)**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	9.900	10.400	0.390	0.409
B	1.270 TYP		0.050 TYP	
C	8.500	8.900	0.335	0.350
D	13.300	13.800	0.524	0.543
E	1.120	1.420	0.044	0.056
F	0.660	0.960	0.026	0.038
G	2.540 TYP		0.100 TYP	
H	1.120	1.420	0.044	0.056
J	4.320	4.820	0.170	0.190
K	0.280	0.520	0.011	0.200
L	4.460	4.860	0.176	0.191
M	1.430	1.630	0.056	0.064

**Order Information**

Device	Package	Marking	Packaging	SPQ
GSFDT4022	TO-262-3L	DT4022	Tube	50 Pcs / Tube